October 20 (Tue.), 2026

[Oral 02] CMP for Advanced Interconnects (II)

11:35-12:55

International Conference Hall (B1F)

● Session Chair: Rob Rhoades (Kothar Technologies, USA)

11:35-11:55 [Oral 02-1]	Advanced Logic Dummy Gate Planarization Challenges	Catarina Regra da Silva, Bart Kenens, and Kevin Vandersmissen (imec, Belgium)
11:55-12:15 [Oral 02-2]	Development of ILD CMP for Enhanced Fence Removal Efficiency	Jihyun An (Samsung Electronics Co., Ltd., Korea) and Kihoon Jang (Samsung Electronics Co., Ltd., Korea)
12:15-12:35 [Oral 02-3]	STI CMP with Mesoporous Nano Ceria Particles	Linyi Shen, Boao Ma, Wenlong Tang, Wei Yuan, Fan Zhang, and Xin-Ping Qu (Fudan Univ., China)
12:35-12:55 [Oral 02-4]	Slurry Activation with Megasonics in Barrier CMP	H. Hiyama, A. Manzonie, J.C. Yang, T. Kajikawa, M. Rahman (Ebara Corp., Japan), A. Philipossian, Y. Sampurno (Araca, Inc., USA), C. J. Keating, and J. J. Keleher (Lewis Univ., USA)